



<p>Milano, 19/06/24 FROM: RADICE ROBERTO</p> <p>In case of purchase, send your order to: orders@electron-mec.com</p> <p>ATTN: MATTEO D'ANDREA</p>	<p>TO: INAF ROMA VIA DEL FOSSO DEL CAVALIERE, 100</p> <p>00133 ROMA</p> <p>P.IVA-VAT:06895721006</p>
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<p>QUOTATION NO. 3448 REF: TPT</p>	<p>TERMS OF PAYMENT: B.B. 1 MESE D.F. F.M.</p>
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P/N	DESCRIPTION	UNIT PRICE EUR	QUANTITY	TOTAL PRICE EUR
H69-1	Bond Starter Kit for HB16 Wedge & Ball Bonder H69-1 - Starter Kit for HB16 For Wedge & Ball Bonder, including: H60-21 - Gold Wedge 25µm - 3 pcs H61-1 - Capillary 25µm 11mm - 3 pcs H60-40 - Aluminum Wedge 25µm - 3 pcs H70-21 - Gold Wire 25µm, 100m, HD2 - 1 pc H74-41 - Aluminum Wire 25µm, 100m, AISi 1% - 1 pc H68-2 - TPT PCB Bond Sample - 3 pcs H65 - Unplugging Probe Needle - 25 pcs H66 - Unplugging Tungsten Wire - 10 pcs H67 - TPT Tweezers - 2 pcs	1.715,00	1	1.715,00
E-DAP	Equipment import, crating and documentation fees, Insurance, delivery DAP	210,00	1	210,00

<p>VAT NOT INCLUDED</p> <p>QUOTATION VALIDITY: 19/07/24</p> <p>INCOTERMS 2020 DAP Roma</p> <p>WARRANTY: NA</p> <p>DELIVERY TIME: 8 WEEKS ARO</p>	<p>T&C: https://www.electron-mec.com/cgv/</p>	<p>Pagina 1 di 1</p> <table border="1" style="width: 100%;"> <tr> <td style="width: 70%;">TOTALE EUR</td> <td style="width: 30%; text-align: right;">1.925,00</td> </tr> </table>	TOTALE EUR	1.925,00
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